

## IEEE Components, Packaging and Manufacturing Technology Society OC Chapter

Thursday, July 17, 2014 Technical Meeting

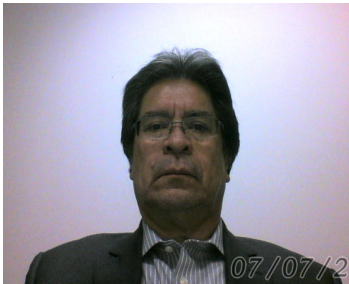
### The Development of Advanced Leadframes

Emerson Erazo, Mitsui High-tec

#### Abstract

Mitsui High-tec is a leading supplier of lead frame tooling for the semiconductor industry. This presentation will cover the development of advanced lead frames, including new design and plating technology offering higher packaging density and reliability.

#### Biography



Emerson Erazo is a senior sales executive with a total of 33 years of experience in the semiconductor industry - 10 years in manufacturing /quality engineering and 23 years in sales, He has held management positions in OSAT companies as well as lead frame manufacturing companies, and is currently managing the Mitsui High-tec, Inc. sales office in the Americas. Mr. Erazo has a BS in Agricultural Engineering from the Catholic University of El Salvador UCA Jose Simeon Canas and is a certified quality engineer.

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Date: **Thursday, July 17, 2014**

Location: **Broadcom Corporation, 5300 California Ave., Irvine, CA 92617 – Crystal Cove 2-1032**

Check in at the Security Gate and proceed to Bldg. 2. You will be escorted into the building.

Time: **5:30-6:00pm: Social time, 6:00-7:00pm: Presentation, 7:00pm: Dinner (free for attendees!)**

RSVP: **IEEE members and non-members all are welcome. Please RSVP at**  
<http://tinyurl.com/mhunbxb>

Please be at the Bldg. 2 entrance by 6:00 pm; no escorts after that. For questions regarding RSVP, please contact Zijie Cai ([zijiecai@broadcom.com](mailto:zijiecai@broadcom.com)).

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**For more information please contact the following officers of the IEEE CPMT OC Chapter:**

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